WHAT IS CLAIMED IS:

1. A dressing board for dressing a cutting blade for cutting a workpiece, the dressing board being adapted to be cut by the cutting blade, thereby dressing the cutting blade, the dressing board comprising:

a substrate not containing abrasive grains; and

a dressing member provided on the substrate and containing abrasive grains;

the substrate and the dressing member coming into contact with the cutting blade in dressing the cutting blade, thereby wearing the cutting blade, wherein

the substrate is formed of the same material as that of the workpiece.

2. The dressing board according to claim 1, wherein the substrate has a thickness which is set to a value greater than or equal to the thickness of the dressing member.

3. The dressing board according to claim 1, wherein the thickness of the substrate is in a range of 0.2 to 1 mm, and

the thickness of the dressing member is in a range of 0.05 to 1 mm.

4. A dressing method for dressing a cutting blade for cutting a workpiece, by using a dressing board

including a substrate not containing abrasive grains and a dressing member provided on the substrate and containing abrasive grains, the dressing method comprising:

a holding step of holding the substrate side of the dressing board on a chuck table included in a cutting apparatus; and

a dressing step of making the cutting blade cut the dressing member side of the dressing board after performing the holding step, thereby cutting both the dressing member and the substrate by using the cutting blade.